



# TPSM84209 4.5V~28V入力、1.2V~6V出力、2.5A電源モジュール

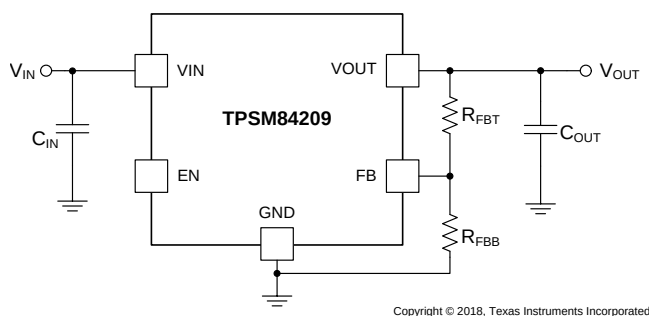
## 1 特長

- 小さな占有面積で低プロファイルの設計を可能にする完全な統合電源ソリューション
- 4.5mm×4mm×2mmのQFNパッケージ
- 広い出力電圧範囲(1.2V~6V)
- 固定スイッチング周波数(750kHz)
- 高度な Eco-mode™ による軽負荷時の効率向上
- 低電圧誤動作防止(UVLO)をプログラム可能
- 過熱時のサーマル・シャットダウン保護
- 過電流保護(ヒカッパ・モード)
- 安全なプリバイアス出力によるスタートアップ
- 動作時のIC接合部温度範囲: -40°C~+125°C
- 動作時周囲温度範囲: -40°C~+85°C
- 強化された熱特性: 29.5°C/W
- EN55011の放射EMI規格に準拠
  - シールド付きインダクタを内蔵
- WEBENCH® Power Designerにより、TPSM84209を使用するカスタム設計を作成

## 2 アプリケーション

- 産業用およびモータ制御
- 自動テスト機器
- 医療用およびイメージング機器
- 高密度の電源システム

アプリケーション概略図



## 3 概要

TPSM84209電源モジュールは、2.5AのDC/DCコンバータ、シールド付きインダクタ、およびパッシブ部品を薄型のQFNパッケージに内蔵した、使いやすい統合電源です。この総合的な電源ソリューションは、わずか4個の外付け部品で動作し、特定の設計要件に応じて主要なパラメータを変更する機能もあります。

TPSM84209デバイスは入力電圧範囲が広く、パッケージ・サイズが小さいため、2.5Aの出力電流を必要とする電源レールに最適です。

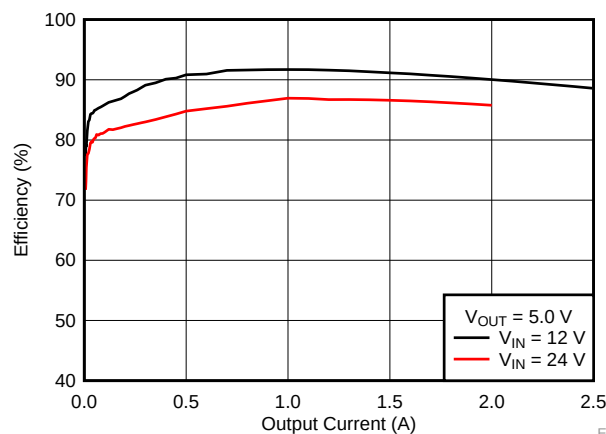
QFNパッケージはプリント基板へ簡単にハンダ付けでき、消費電力特性が非常に優れています。TPSM84209は柔軟で、多くの機能を持ち、広範なデバイスおよびシステムの電源として理想的です。

製品情報<sup>(1)</sup>

| デバイス番号    | パッケージ   | 本体サイズ         |
|-----------|---------|---------------|
| TPSM84209 | QFN (9) | 4.50mm×4.00mm |

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

効率と出力電流との関係



E113



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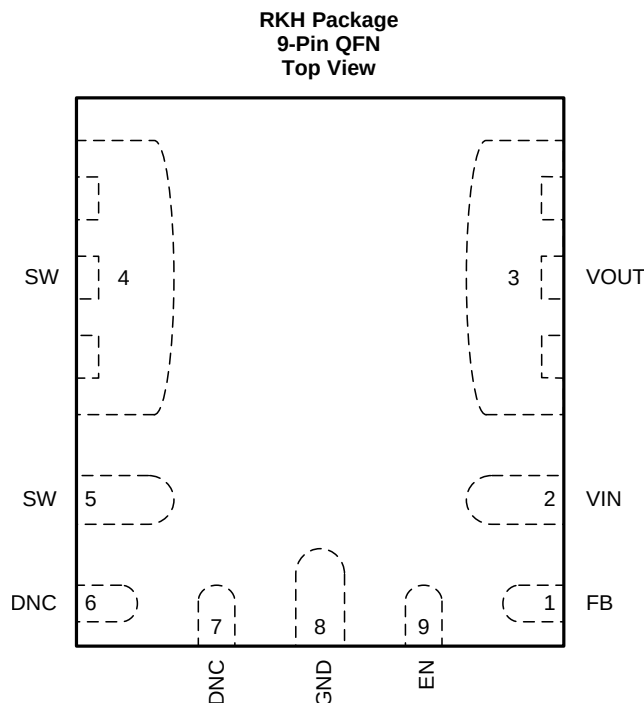
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## 4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

|                                                                               |             |
|-------------------------------------------------------------------------------|-------------|
| <b>Revision B (June 2018) から Revision C に変更</b>                               | <b>Page</b> |
| • パッケージの列を「B3QFN (43)」から「QFN (9)」に変更 .....                                    | 1           |
| • Changed "RVQ Package" to "RKH Package", "43-pin B3QFN" to "9-Pin QFN" ..... | 3           |
| <b>Revision A (April 2018) から Revision B に変更</b>                              | <b>Page</b> |
| • Changed Min Storage temperature to $-55^{\circ}\text{C}$ .....              | 4           |
| <b>2018年1月発行のものから更新</b>                                                       | <b>Page</b> |
| • 量産版データシートの初版リリース .....                                                      | 1           |

## 5 Pin Configuration and Functions



**Pin Functions**

| PIN  |      | TYPE <sup>(1)</sup> | DESCRIPTION                                                                                                                                                                                                                                                                                                              |
|------|------|---------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| NAME | NO.  |                     |                                                                                                                                                                                                                                                                                                                          |
| DNC  | 6, 7 | —                   | Do Not Connect. Do not connect these pins to GND or to any other voltage. These pins are connected to internal circuitry. Each pin must be soldered to an isolated pad.                                                                                                                                                  |
| EN   | 9    | I                   | Enable pin. An open drain/collector device can be used to control the EN function. The module is disabled when this pin is pulled low. This pin can also be connected to an external resistor divider connected between VIN and GND to adjust the UVLO above the internal default setting. Float this pin when not used. |
| FB   | 1    | I                   | Feedback input. To adjust the output voltage connect this pin to the center point of an external resistor divider connected between VOUT and GND.                                                                                                                                                                        |
| GND  | 8    | G                   | Ground pin. This is the return current path for the device. Connect this pin to the input source return, the load return, and to the ground side of the VIN and VOUT bypass capacitors using power ground planes on the PCB.                                                                                             |
| SW   | 4, 5 | O                   | Switch node. These pins are connected to the input side of the internal output inductor. Do not place any external components on these pins or tie them to a pin of another function.                                                                                                                                    |
| VIN  | 2    | I                   | Input voltage. Connect this pin to the input source and connect external bypass capacitors between this pin and GND, close to the module.                                                                                                                                                                                |
| VOUT | 3    | O                   | Output voltage. This pin is connected to the internal output inductor. Connect this pin to the output load and connect external bypass capacitors between this pin and GND close to the module.                                                                                                                          |

(1) G = Ground, I = Input, O = Output

## 6 Specifications

### 6.1 Absolute Maximum Ratings

Over operating ambient temperature range (unless otherwise noted)<sup>(1)</sup>

|                                                                  |                                                        | MIN  | MAX  | UNIT |
|------------------------------------------------------------------|--------------------------------------------------------|------|------|------|
| Input voltage                                                    | VIN                                                    | –0.3 | 30   | V    |
|                                                                  | EN, FB                                                 | –0.3 | 7    | V    |
| Output voltage                                                   | SW                                                     | –0.3 | 30   | V    |
|                                                                  | SW (20 ns transient)                                   | –5   | 30   | V    |
|                                                                  | VOUT                                                   | –0.3 | 7    | V    |
| Mechanical shock                                                 | Mil-STD-883D, Method 2002.3, 1 msec, 1/2 sine, mounted |      | 1500 | G    |
| Mechanical vibration                                             | Mil-STD-883D, Method 2007.2, 20 to 2000 Hz             |      | 20   | G    |
| Operating IC junction temperature, T <sub>J</sub> <sup>(2)</sup> |                                                        | –40  | 125  | °C   |
| Operating ambient temperature, T <sub>A</sub> <sup>(2)</sup>     |                                                        | –40  | 85   | °C   |
| Storage temperature, T <sub>stg</sub>                            |                                                        | –55  | 150  | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under the recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The ambient temperature is the air temperature of the surrounding environment. The junction temperature is the temperature of the internal power IC when the device is powered. Operating below the maximum ambient temperature, as shown in the safe operating area (SOA) curves in the typical characteristics sections, ensures that the maximum junction temperature of any component inside the module is never exceeded.

### 6.2 ESD Ratings

|                                            |                                                                                | VALUE | UNIT |
|--------------------------------------------|--------------------------------------------------------------------------------|-------|------|
| V <sub>(ESD)</sub> Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>              | ±2500 | V    |
|                                            | Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup> | ±1000 |      |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

Over operating ambient temperature range (unless otherwise noted)

|                                                   | MIN                | MAX                | UNIT |
|---------------------------------------------------|--------------------|--------------------|------|
| Input voltage, V <sub>IN</sub>                    | 4.5 <sup>(1)</sup> | 28 <sup>(2)</sup>  | V    |
| Output voltage, V <sub>OUT</sub>                  | 1.2                | 6                  | V    |
| EN voltage, V <sub>EN</sub>                       | 0                  | 6                  | V    |
| Output current, I <sub>OUT</sub>                  | 0                  | 2.5 <sup>(3)</sup> | A    |
| Operating ambient temperature, T <sub>A</sub>     | –40                | 85                 | °C   |
| Operating IC junction temperature, T <sub>J</sub> | –40                | 125                |      |

- (1) The minimum recommended input voltage is 4.5 V or (V<sub>OUT</sub> × 1.3), whichever is greater.
- (2) The maximum input voltage varies depending on the output voltage (see [Operating Range](#)).
- (3) The maximum output current that the TPSM84209 can deliver is a function of input voltage, output voltage, and ambient temperature (see [Output Current Rating](#)).

## 6.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |                                                             | TPSM84209 | UNIT |
|-------------------------------|-------------------------------------------------------------|-----------|------|
|                               |                                                             | RKH (QFN) |      |
|                               |                                                             | 9 PINS    |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance <sup>(2)</sup>       | 32.7      | °C/W |
| ψ <sub>JT</sub>               | Junction-to-top characterization parameter <sup>(3)</sup>   | 2.2       | °C/W |
| ψ <sub>JB</sub>               | Junction-to-board characterization parameter <sup>(4)</sup> | 17        | °C/W |

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).
- (2) The junction-to-ambient thermal resistance, R<sub>θJA</sub>, applies to devices soldered directly to a 63 mm × 50 mm, 4-layer PCB with 2 oz. copper and natural convection cooling. Additional airflow reduces R<sub>θJA</sub>.
- (3) The junction-to-top characterization parameter, ψ<sub>JT</sub>, estimates the junction temperature, T<sub>J</sub>, of a device in a real system, using a procedure described in JESD51-2A (section 6 and 7). T<sub>J</sub> = ψ<sub>JT</sub> × P<sub>dis</sub> + T<sub>T</sub>; where P<sub>dis</sub> is the power dissipated in the device and T<sub>T</sub> is the temperature of the top of the device.
- (4) The junction-to-board characterization parameter, ψ<sub>JB</sub>, estimates the junction temperature, T<sub>J</sub>, of a device in a real system, using a procedure described in JESD51-2A (sections 6 and 7). T<sub>J</sub> = ψ<sub>JB</sub> × P<sub>dis</sub> + T<sub>B</sub>; where P<sub>dis</sub> is the power dissipated in the device and T<sub>B</sub> is the temperature of the board 1mm from the device.

## 6.5 Electrical Characteristics

Over –40°C to +85°C ambient temperature, V<sub>IN</sub> = 12 V, V<sub>OUT</sub> = 3.3 V, I<sub>OUT</sub> = 2.5 A, (unless otherwise noted); C<sub>IN1</sub> = 10 μF, 50 V, 1210 ceramic; C<sub>IN2</sub> = 100-μF, 35-V, electrolytic; C<sub>OUT</sub> = 2 × 47-μF, 16-V, 1210 ceramic. Minimum and maximum limits are guaranteed through production test or by design. Typical values represent the expected value for the given test conditions and may or may not be production tested.

| PARAMETER                          |                                      | TEST CONDITIONS                                                                 | MIN                      | TYP   | MAX                | UNIT |
|------------------------------------|--------------------------------------|---------------------------------------------------------------------------------|--------------------------|-------|--------------------|------|
| INPUT VOLTAGE (V <sub>IN</sub> )   |                                      |                                                                                 |                          |       |                    |      |
| V <sub>IN</sub>                    | Input voltage                        | Over I <sub>OUT</sub> range                                                     | 4.5 <sup>(1)</sup>       |       | 28 <sup>(2)</sup>  | V    |
| UVLO                               | V <sub>IN</sub> undervoltage lockout | V <sub>IN</sub> increasing                                                      | 3.8                      | 4.1   | 4.4                | V    |
|                                    |                                      | V <sub>IN</sub> decreasing                                                      | 3.3                      | 3.6   | 3.9                | V    |
| I <sub>SHDN</sub>                  | Shutdown supply current              | V <sub>EN</sub> = 0 V                                                           | 2                        |       |                    | μA   |
| OUTPUT VOLTAGE (V <sub>OUT</sub> ) |                                      |                                                                                 |                          |       |                    |      |
| V <sub>OUT(ADJ)</sub>              | Output voltage adjust                | Over I <sub>OUT</sub> range                                                     | 1.2                      |       | 6                  | V    |
| V <sub>OUT(Ripple)</sub>           | Output voltage ripple                | 20-MHz bandwidth                                                                | 22                       |       |                    | mV   |
| FEEDBACK                           |                                      |                                                                                 |                          |       |                    |      |
| V <sub>FB</sub>                    | Feedback voltage <sup>(3)</sup>      | T <sub>A</sub> = 25°C, I <sub>OUT</sub> = 0.2 A                                 | 0.581                    | 0.596 | 0.611              | V    |
|                                    | Temperature variation                | –40°C ≤ T <sub>J</sub> ≤ 125°C, I <sub>OUT</sub> = 0.2 A                        | 0.5%                     |       |                    |      |
|                                    | Line regulation                      | T <sub>A</sub> = 25°C, 4.5 V ≤ V <sub>IN</sub> ≤ 28 V, I <sub>OUT</sub> = 0.2 A | 0.2                      |       |                    | %    |
|                                    | Load regulation                      | Over I <sub>OUT</sub> range, T <sub>A</sub> = 25°C                              | 0.5                      |       |                    | %    |
| CURRENT                            |                                      |                                                                                 |                          |       |                    |      |
| I <sub>OUT</sub>                   | Output current                       | Natural convection, T <sub>A</sub> = 25°C                                       | 0                        |       | 2.5 <sup>(4)</sup> | A    |
|                                    | Overcurrent threshold                |                                                                                 | 4.8                      |       |                    | A    |
| PERFORMANCE                        |                                      |                                                                                 |                          |       |                    |      |
| η                                  | Efficiency                           | V <sub>IN</sub> = 24 V,<br>I <sub>OUT</sub> = 1 A                               | V <sub>OUT</sub> = 5 V   | 86.5% |                    |      |
|                                    |                                      |                                                                                 | V <sub>OUT</sub> = 3.3 V | 82.7% |                    |      |
|                                    |                                      |                                                                                 | V <sub>OUT</sub> = 2.5 V | 79.3% |                    |      |
|                                    |                                      | V <sub>IN</sub> = 12 V,<br>I <sub>OUT</sub> = 1 A                               | V <sub>OUT</sub> = 5 V   | 91.7% |                    |      |
|                                    |                                      |                                                                                 | V <sub>OUT</sub> = 3.3 V | 89.0% |                    |      |
|                                    |                                      |                                                                                 | V <sub>OUT</sub> = 2.5 V | 86.8% |                    |      |
| Transient response                 |                                      | 25% to 75% load step<br>1 A/μs slew rate                                        | Over/undershoot          | 90    |                    | mV   |
|                                    |                                      |                                                                                 | Recovery Time            | 125   |                    | μs   |

- (1) The minimum recommended input voltage is 4.5 V or (V<sub>OUT</sub> × 1.3), whichever is greater.
- (2) The maximum input voltage varies depending on the output voltage (see [Operating Range](#)).
- (3) The overall output voltage tolerance will be affected by the tolerance of the external R<sub>FBT</sub> and R<sub>FBB</sub> resistors.
- (4) The maximum output current that the TPSM84209 can deliver is a function of input voltage, output voltage, and ambient temperature (see [Output Current Rating](#)).

## Electrical Characteristics (continued)

Over  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  ambient temperature,  $V_{\text{IN}} = 12\text{ V}$ ,  $V_{\text{OUT}} = 3.3\text{ V}$ ,  $I_{\text{OUT}} = 2.5\text{ A}$ , (unless otherwise noted);  $C_{\text{IN}1} = 10\text{ }\mu\text{F}$ , 50 V, 1210 ceramic;  $C_{\text{IN}2} = 100\text{-}\mu\text{F}$ , 35-V, electrolytic;  $C_{\text{OUT}} = 2 \times 47\text{-}\mu\text{F}$ , 16-V, 1210 ceramic. Minimum and maximum limits are guaranteed through production test or by design. Typical values represent the expected value for the given test conditions and may or may not be production tested.

| PARAMETER              |                             | TEST CONDITIONS         | MIN                                   | TYP  | MAX | UNIT |
|------------------------|-----------------------------|-------------------------|---------------------------------------|------|-----|------|
| SOFT START             |                             |                         |                                       |      |     |      |
| T <sub>SS</sub>        | Internal soft-start time    |                         | 5                                     |      |     | ms   |
| SWITCHING FREQUENCY    |                             |                         |                                       |      |     |      |
| F <sub>SW</sub>        | Switching frequency         |                         | 578                                   | 750  | 923 | kHz  |
| ENABLE (EN)            |                             |                         |                                       |      |     |      |
| V <sub>EN-RISING</sub> | EN threshold                | Rising                  | 1.21                                  | 1.28 |     | V    |
| V <sub>EN-FALLIN</sub> |                             | Falling                 | 1.1                                   | 1.19 |     | V    |
| I <sub>EN</sub>        | EN Input current            | V <sub>EN</sub> = 1 V   | 0.7                                   |      |     | μA   |
|                        | EN Hysteresis current       | V <sub>EN</sub> = 1.5 V | 1.55                                  |      |     | μA   |
| THERMAL                |                             |                         |                                       |      |     |      |
| T <sub>SHDN</sub>      | Thermal shutdown            | Shutdown temperature    | 165                                   |      |     | °C   |
|                        |                             | Hysteresis              | 10                                    |      |     | °C   |
| CAPACITANCE            |                             |                         |                                       |      |     |      |
| C <sub>IN</sub>        | External input capacitance  | Ceramic type            | 10 <sup>(5)</sup>                     |      |     | μF   |
|                        |                             | Non-ceramic type        | 47 <sup>(5)</sup>                     |      |     | μF   |
| C <sub>OUT</sub>       | External output capacitance | Ceramic type            | min <sup>(6)</sup> 500 <sup>(7)</sup> |      |     | μF   |
|                        |                             | Non-ceramic type        | 500 <sup>(7)</sup>                    |      |     | μF   |

- (5) A minimum of 10  $\mu\text{F}$  ceramic input capacitance is required for proper operation. An additional 47  $\mu\text{F}$  of bulk capacitance is recommended for applications with transient load requirements.
- (6) The minimum amount of required output capacitance varies depending on the output voltage (see [Output Capacitor Selection](#)). A minimum amount of ceramic capacitance is required. Locate the capacitance close to the device. Adding additional ceramic or non-ceramic capacitance close to the load improves the response of the regulator to load transients.
- (7) The maximum output capacitance of 500  $\mu\text{F}$  can be made up of all ceramic type or a combination of both ceramic and non-ceramic type.

## 6.6 Typical Characteristics ( $V_{IN} = 5\text{ V}$ )

$T_A = 25^\circ\text{C}$ , unless otherwise noted.

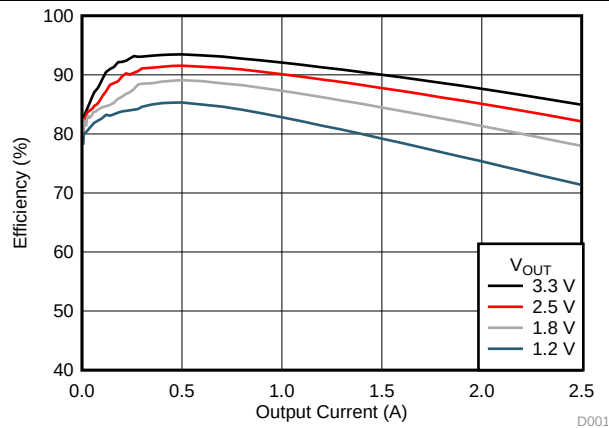


Figure 1. Efficiency vs Output Current

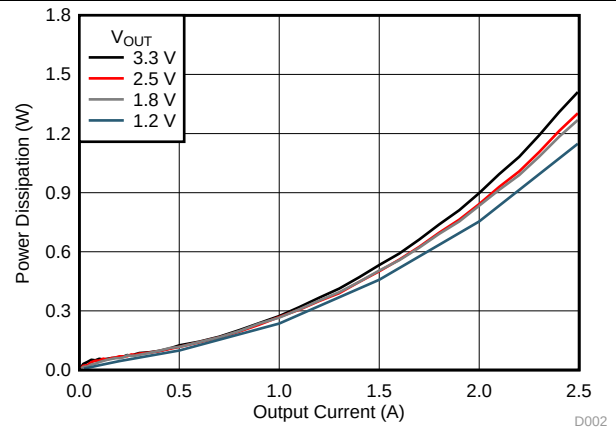


Figure 2. Power Dissipation vs Output Current

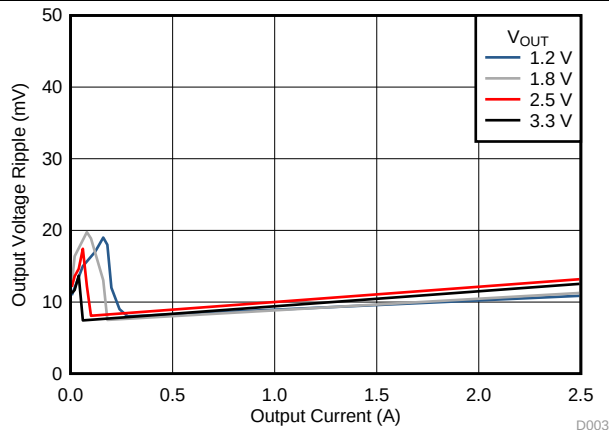


Figure 3. Voltage Ripple vs Output Current

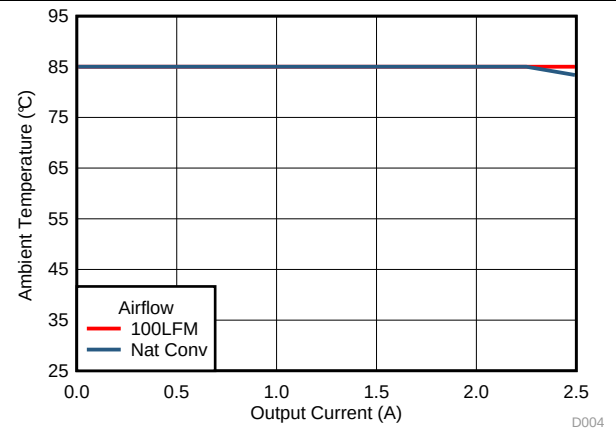


Figure 4. Safe Operating Area

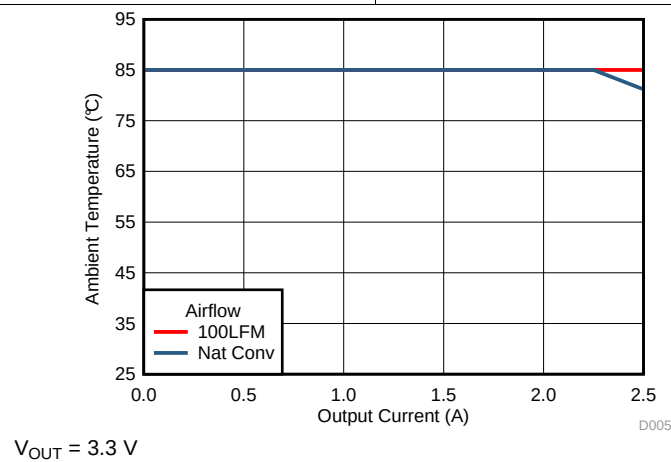


Figure 5. Safe Operating Area

## 6.7 Typical Characteristics ( $V_{IN} = 12\text{ V}$ )

$T_A = 25^\circ\text{C}$ , unless otherwise noted.

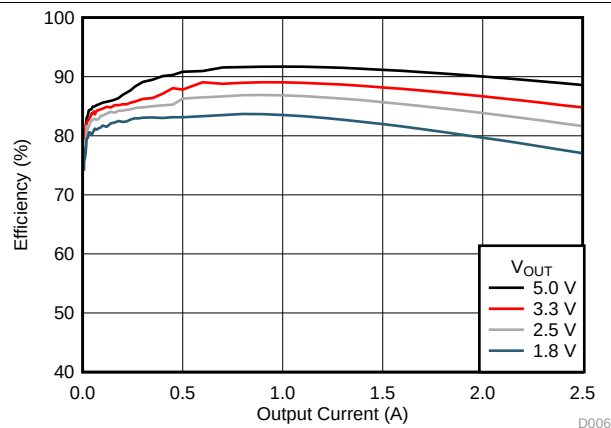


图 6. Efficiency vs Output Current

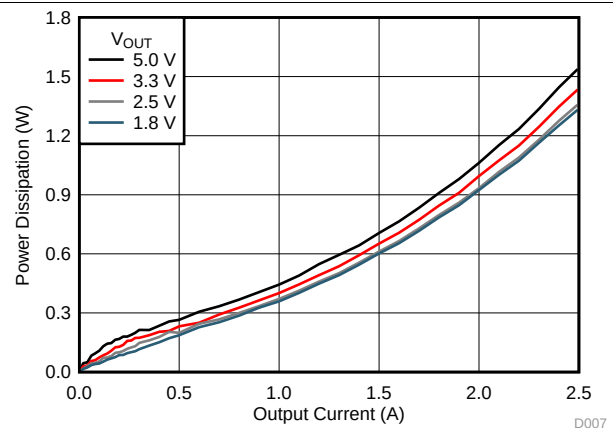


图 7. Power Dissipation vs Output Current

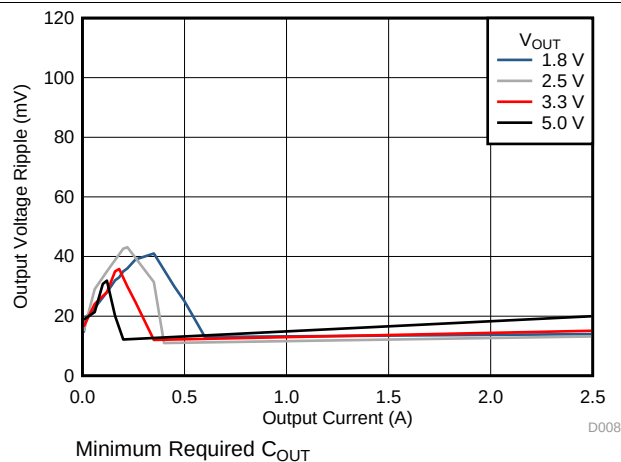


图 8. Voltage Ripple vs Output Current

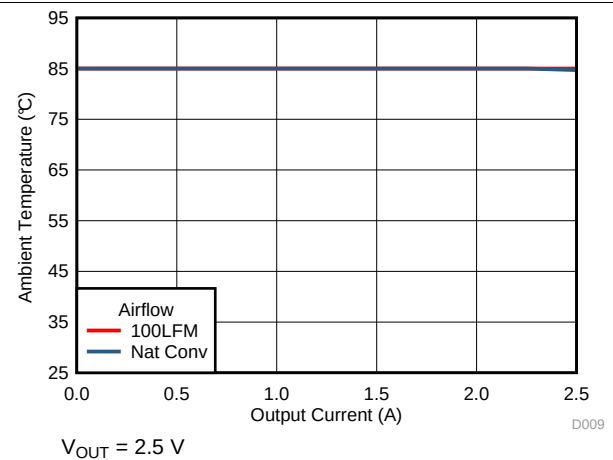


图 9. Safe Operating Area

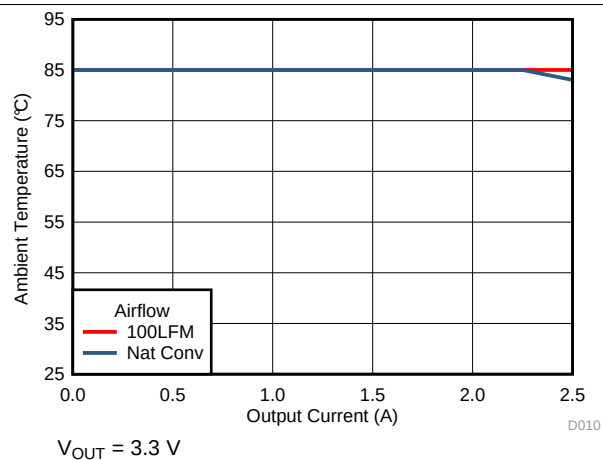


图 10. Safe Operating Area

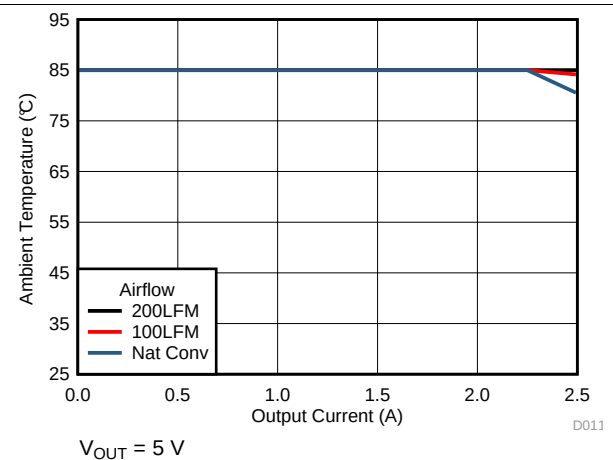


图 11. Safe Operating Area

## 6.8 Typical Characteristics ( $V_{IN} = 24\text{ V}$ )

$T_A = 25^\circ\text{C}$ , unless otherwise noted.

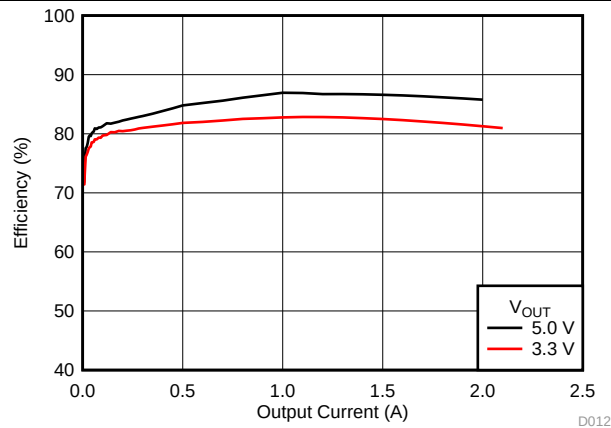


FIG 12. Efficiency vs Output Current

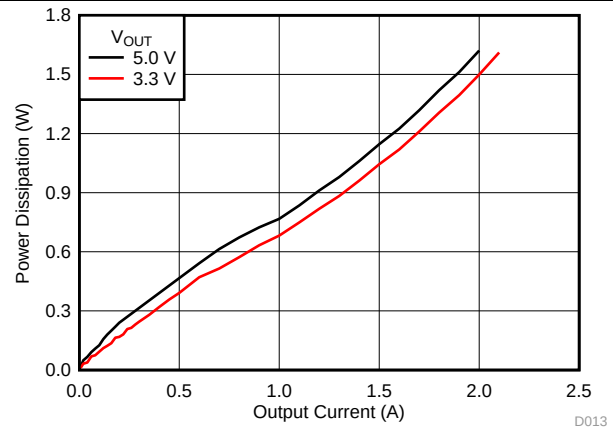


FIG 13. Power Dissipation vs Output Current

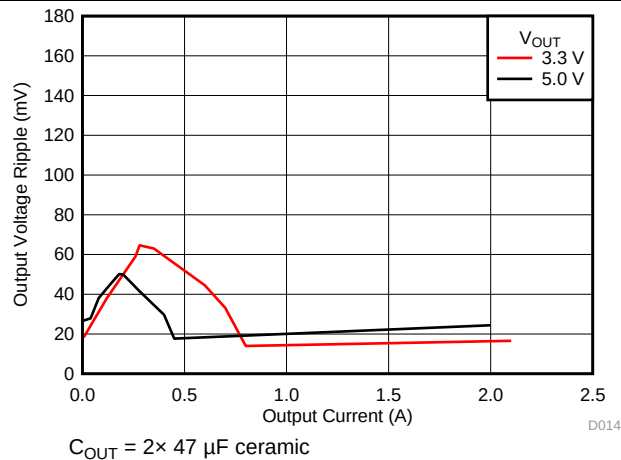


FIG 14. Voltage Ripple vs Output Current

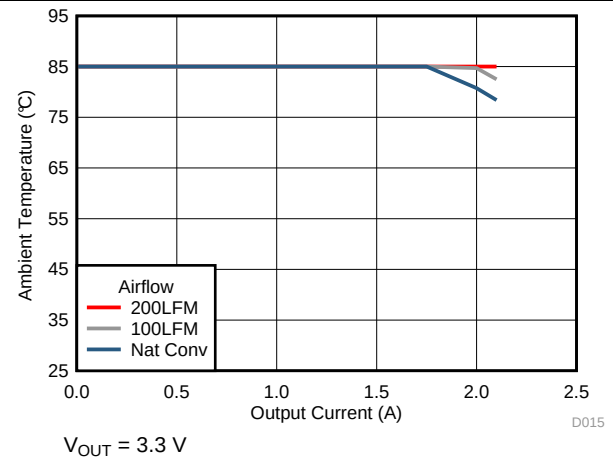


FIG 15. Safe Operating Area

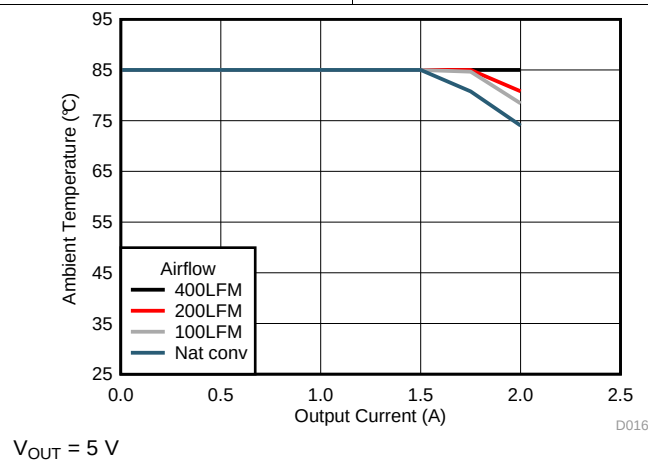


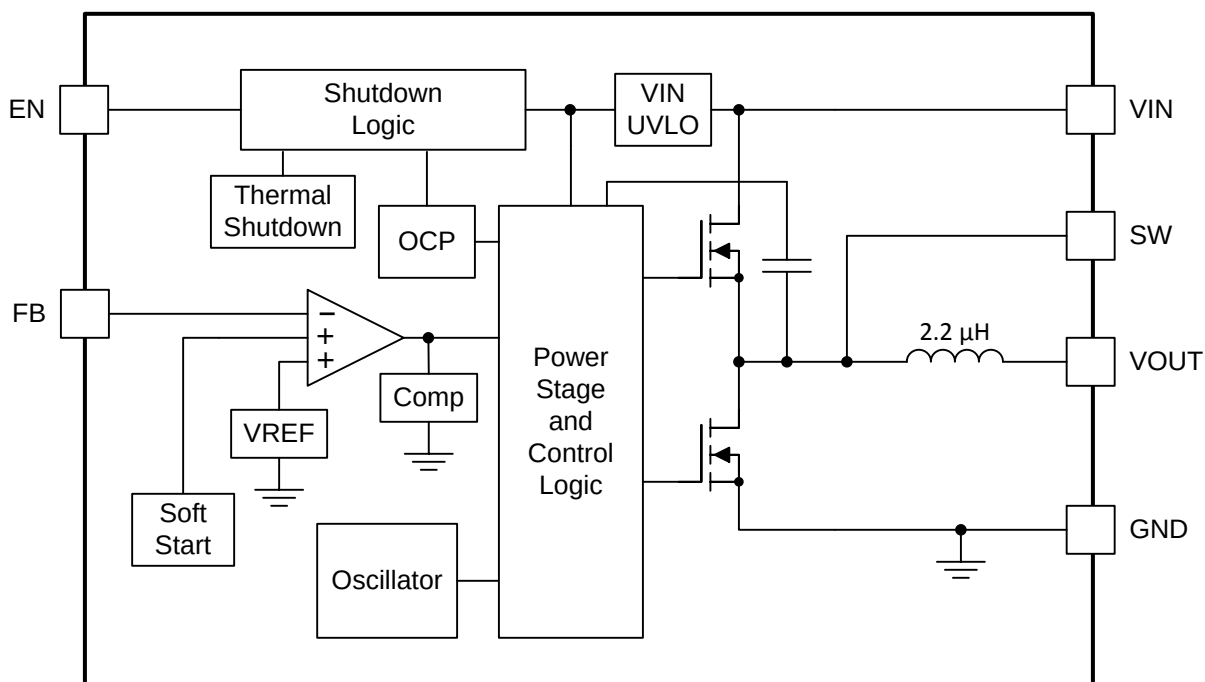
FIG 16. Safe Operating Area

## 7 Detailed Description

### 7.1 Overview

The TPSM84209 is a highly integrated 28-V input, 2.5-A, synchronous step-down power module with PWM, MOSFETs, inductor, and control circuitry integrated into a low-profile, overmolded, QFN package. This device enables small designs by integrating all but the input and output capacitors and voltage-setting resistor divider while keeping the ability to adjust key parameters to meet specific design requirements. The TPSM84209 operates at a 750-kHz fixed switching frequency and features advanced Eco-mode™ pulse-skip operation for improved light-load efficiency. The TPSM84209 provides an adjustable output-voltage range of 1.2 V to 6 V using a simple external-resistor divider. The TPSM84209 provides accurate voltage regulation for a variety of loads by using an internal voltage reference that is 2.5% accurate over temperature. The output-voltage rise time is controlled by a fixed 5-ms soft start. Input UVLO is internally set at 4.1 V, but can be adjusted upward using a resistor divider on the EN pin of the module. The EN pin can also be pulled low to put the module in standby mode to reduce input quiescent current. Thermal shutdown and current limit features protect the device during an overload condition. A 9-pin, 4-mm × 4.5-mm B3QFN package that includes exposed bottom pads provides a thermally enhanced solution for space-constrained applications.

### 7.2 Functional Block Diagram



## 7.3 Feature Description

### 7.3.1 Adjusting the Output Voltage

A resistor divider connected to the FB pin (pin 1) programs the output voltage of the TPSM84209. The output voltage adjustment range is from 1.2 V to 6 V. 図 17 shows the feedback resistor connection for setting the output voltage. The recommended value of  $R_{FBT}$  is 10 kΩ. 表 1 lists the closest standard E96 value for the  $R_{FBB}$  resistor for a number of common output voltages. For other output voltages, the value of the required  $R_{FBB}$  resistor can be calculated using 式 1.

$$R_{FBB} = \frac{6}{(V_{OUT} - 0.6)} \quad (\text{k}\Omega) \quad (1)$$

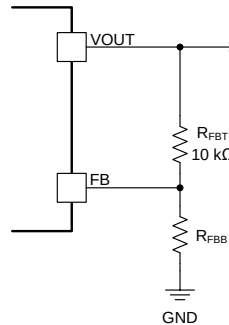


図 17. Setting the Output Voltage

表 1. Standard  $R_{FBB}$  Resistor Values

| $V_{OUT}$ (V) | $R_{FBB}$ (kΩ) | $V_{OUT}$ (V) | $R_{FBB}$ (kΩ) |
|---------------|----------------|---------------|----------------|
| 1.2           | 10.0           | 3.7           | 1.96           |
| 1.3           | 8.45           | 3.8           | 1.87           |
| 1.4           | 7.50           | 3.9           | 1.82           |
| 1.5           | 6.65           | 4.0           | 1.74           |
| 1.6           | 6.04           | 4.1           | 1.69           |
| 1.7           | 5.36           | 4.2           | 1.65           |
| 1.8           | 4.99           | 4.3           | 1.62           |
| 1.9           | 4.64           | 4.4           | 1.58           |
| 2.0           | 4.22           | 4.5           | 1.54           |
| 2.1           | 4.02           | 4.6           | 1.50           |
| 2.2           | 3.74           | 4.7           | 1.47           |
| 2.3           | 3.48           | 4.8           | 1.43           |
| 2.4           | 3.32           | 4.9           | 1.40           |
| 2.5           | 3.16           | 5.0           | 1.37           |
| 2.6           | 3.01           | 5.1           | 1.33           |
| 2.7           | 2.87           | 5.2           | 1.30           |
| 2.8           | 2.74           | 5.3           | 1.27           |
| 2.9           | 2.61           | 5.4           | 1.24           |
| 3.0           | 2.49           | 5.5           | 1.22           |
| 3.1           | 2.37           | 5.6           | 1.20           |
| 3.2           | 2.32           | 5.7           | 1.18           |
| 3.3           | 2.21           | 5.8           | 1.15           |
| 3.4           | 2.15           | 5.9           | 1.13           |
| 3.5           | 2.05           | 6.0           | 1.10           |
| 3.6           | 2.00           |               |                |

### 7.3.2 Input Capacitor Selection

The TPSM84209 requires a ceramic input capacitor with a minimum effective capacitance of 10  $\mu\text{F}$ . Use only high-quality ceramic type X5R or X7R capacitors with sufficient voltage rating. An additional 47  $\mu\text{F}$  of non-ceramic capacitance is recommended for applications with transient load requirements. The voltage rating of input capacitors must be greater than the maximum input voltage. To compensate for the derating of ceramic capacitors, TI recommends a voltage rating of twice the maximum input voltage. At worst case, when operating at 50% duty cycle and maximum load, the combined ripple current rating of the input capacitors must be at least 1.25 Arms. 表 2 includes a preferred list of capacitors by vendor.

**表 2. Recommended Input Capacitors<sup>(1)</sup>**

| VENDOR    | SERIES | PART NUMBER    | CAPACITOR CHARACTERISTICS |                                                 |                                     |
|-----------|--------|----------------|---------------------------|-------------------------------------------------|-------------------------------------|
|           |        |                | WORKING VOLTAGE (V)       | CAPACITANCE <sup>(2)</sup><br>( $\mu\text{F}$ ) | ESR <sup>(3)</sup><br>(m $\Omega$ ) |
| TDK       | X5R    | C3225X5R1H106K | 50                        | 10                                              | 3                                   |
| Murata    | X7R    | GRM32ER71H106K | 50                        | 10                                              | 2                                   |
| Murata    | X7R    | GRM32ER71J106K | 63                        | 10                                              | 2                                   |
| Panasonic | ZA     | EEHZA1H101P    | 50                        | 100                                             | 28                                  |
| Panasonic | ZA     | EEHZA1J560P    | 63                        | 56                                              | 30                                  |

(1) **Capacitor Supplier Verification, RoHS, Lead-free and Material Details**

Consult capacitor suppliers regarding availability, material composition, RoHS and lead-free status, and manufacturing process requirements for any capacitors identified in this table.

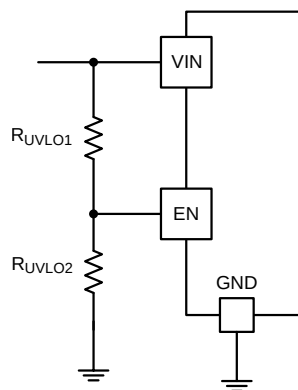
(2) Specified capacitance values

(3) Maximum ESR at 100 kHz, 25°C.

### 7.3.3 Undervoltage Lockout (UVLO)

The TPSM84209 device has an internal UVLO circuit which prevents the device from operating until the  $V_{\text{IN}}$  voltage exceeds the UVLO rising threshold, (4.1 V (typical)). The device is disabled when the  $V_{\text{IN}}$  pin voltage falls below the internal  $V_{\text{IN}}$  UVLO threshold. The internal  $V_{\text{IN}}$  UVLO threshold has a hysteresis of 500 mV.

Applications may require a higher UVLO threshold to prevent early turnon, for sequencing requirements or to prevent input current draw at lower input voltages. An external resistor divider can be added to the EN pin to adjust the UVLO threshold higher. The external resistor divider can be configured as shown in 图 18. 表 3 lists standard values for  $R_{\text{UVLO1}}$  and  $R_{\text{UVLO2}}$  to adjust the UVLO voltage higher.



**图 18. Adjustable UVLO**

**表 3. Standard Resistor Values for Adjusting UVLO**

| $V_{\text{IN}}$ UVLO (V)         | 4.5  | 10   | 15   | 18   | 20   |
|----------------------------------|------|------|------|------|------|
| $R_{\text{UVLO1}}$ (k $\Omega$ ) | 68.1 | 68.1 | 68.1 | 68.1 | 68.1 |
| $R_{\text{UVLO2}}$ (k $\Omega$ ) | 25.5 | 9.53 | 6.04 | 4.99 | 4.42 |

### 7.3.4 Output Capacitor Selection

The minimum amount of required output capacitance for the TPSM84209 varies depending on the output voltage and whether or not a feed-forward capacitor,  $C_{FF}$ , is used (see [Feed-Forward Capacitor](#) for more information on  $C_{FF}$ ). 表 4 lists the minimum output capacitance for several output voltage ranges when not using  $C_{FF}$ . The required output capacitance must be comprised of all ceramic capacitors or a combination of ceramic and polymer-type capacitors. The effects of temperature and capacitor voltage rating must be considered when selecting capacitors to meet the minimum required capacitance.

When adding additional output capacitance, ceramic capacitors or a combination of ceramic and polymer-type capacitors can be used. The required capacitance above the minimum is determined by actual transient deviation requirements. See 表 5 for a preferred list of output capacitors by vendor.

**表 4. Minimum Required Output Capacitance**

| V <sub>OUT</sub> RANGE (V) |       | Minimum Required C <sub>OUT</sub>                   |
|----------------------------|-------|-----------------------------------------------------|
| MIN                        | MAX   |                                                     |
| 1.2                        | < 1.5 | 188 $\mu$ F (4 x 47 $\mu$ F ceramic) <sup>(1)</sup> |
| 1.5                        | < 2.5 | 141 $\mu$ F (3 x 47 $\mu$ F ceramic) <sup>(1)</sup> |
| 2.5                        | < 5   | 94 $\mu$ F (2 x 47 $\mu$ F ceramic)                 |
| 5                          | 6     | 47 $\mu$ F (1 x 47 $\mu$ F ceramic)                 |

(1) The minimum required output capacitance can also be made up of 1 x 47  $\mu$ F ceramic + 1 x 100  $\mu$ F polymer-type capacitor.

**表 5. Recommended Output Capacitors<sup>(1)</sup>**

| VENDOR    | SERIES | PART NUMBER        | CAPACITOR CHARACTERISTICS |                                       |                                  |
|-----------|--------|--------------------|---------------------------|---------------------------------------|----------------------------------|
|           |        |                    | WORKING VOLTAGE (V)       | CAPACITANCE <sup>(2)</sup> ( $\mu$ F) | ESR <sup>(3)</sup> (m $\Omega$ ) |
| TDK       | X5R    | C3225X5R1C106K     | 16                        | 10                                    | 2                                |
| Murata    | X5R    | GRM32ER61C106K     | 16                        | 10                                    | 2                                |
| TDK       | X5R    | C3225X5R1C226M     | 16                        | 22                                    | 2                                |
| Murata    | X5R    | GRM32ER61C226K     | 16                        | 22                                    | 2                                |
| TDK       | X5R    | C3225X5R1A476M     | 10                        | 47                                    | 2                                |
| Murata    | X5R    | GRM32ER61C476K     | 16                        | 47                                    | 3                                |
| TDK       | X5R    | C3225X5R0J107M     | 6.3                       | 100                                   | 2                                |
| Murata    | X5R    | GRM32ER60J107M     | 6.3                       | 100                                   | 2                                |
| Murata    | X5R    | GRM32ER61A107M     | 10                        | 100                                   | 2                                |
| Kemet     | X5R    | C1210C107M4PAC7800 | 16                        | 100                                   | 2                                |
| Panasonic | POSCAP | 6TPE100MI          | 6.3                       | 100                                   | 18                               |
| Panasonic | POSCAP | 6TPF220M9L         | 6.3                       | 220                                   | 9                                |
| Panasonic | POSCAP | 6TPE220ML          | 6.3                       | 220                                   | 12                               |

(1) **Capacitor Supplier Verification, RoHS, Lead-free and Material Details**

Consult capacitor suppliers regarding availability, material composition, RoHS and lead-free status, and manufacturing process requirements for any capacitors identified in this table.

(2) Specified capacitance values.

(3) Maximum ESR at 100 kHz, 25°C.

### 7.3.5 Feed-Forward Capacitor

The TPSM84209 is internally compensated to be stable over the operating range of the device. However, depending on the output voltage and amount of output capacitance, an additional feed-forward capacitor,  $C_{FF}$ , may be added for optimum performance. Adding additional output capacitance above the minimum reduces the output voltage ripple of the device. However, adding additional output capacitance also reduces the cross-over frequency of the device, slowing the response to load transients. Adding a feed-forward capacitor when adding more output capacitance helps to restore cross-over frequency of the device, restoring the transient response.

The external feed-forward capacitor must be placed in parallel with the top resistor divider,  $R_{FBT}$ . The placement of  $C_{FF}$  is shown in 图 19. 表 6 lists the required  $C_{FF}$  values for different amounts of output capacitance. For output voltages < 2.5 V, it is not recommended to add a  $C_{FF}$  capacitor.

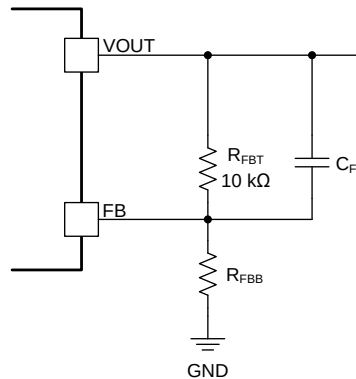


图 19. Feed-Forward Capacitor

表 6.  $C_{FF}$  Values<sup>(1)</sup>

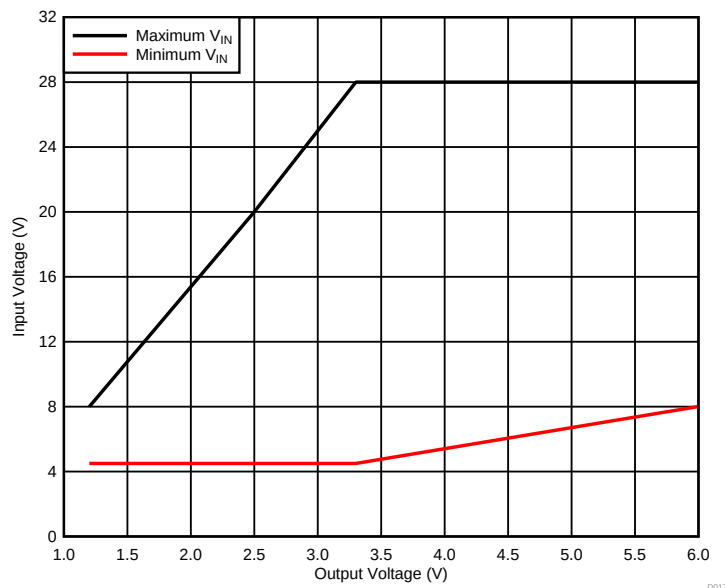
| $V_{OUT}$ RANGE (V) |       | Amount of $C_{OUT}$         |                             |                              |                                     |
|---------------------|-------|-----------------------------|-----------------------------|------------------------------|-------------------------------------|
| MIN                 | MAX   | 47 $\mu$ F (1 x 47 $\mu$ F) | 94 $\mu$ F (2 x 47 $\mu$ F) | 141 $\mu$ F (3 x 47 $\mu$ F) | $\geq 188$ $\mu$ F (4 x 47 $\mu$ F) |
| 2.5                 | < 3.3 | Not applicable              | $C_{FF} = 100$ pF           | $C_{FF} = 220$ pF            | $C_{FF} = 330$ pF                   |
| 3.3                 | < 5   | Not applicable              | $C_{FF} = 100$ pF           | $C_{FF} = 330$ pF            | $C_{FF} = 330$ pF                   |
| 5                   | 6     | $C_{FF} = 100$ pF           | $C_{FF} = 330$ pF           | $C_{FF} = 330$ pF            | $C_{FF} = 330$ pF                   |

(1) The  $C_{FF}$  values listed in this table apply when  $R_{FBT} = 10$  k $\Omega$ . To calculate the value of  $C_{FF}$  when using another  $R_{FBT}$  value, multiply the  $C_{FF}$  value listed in the table by  $10$  k $\Omega$  /  $R_{FBT}$ .

### 7.3.6 Operating Range

The TPSM84209 operates over a wide input voltage and output voltage range; however, not all output voltages can operate over the entire input voltage range. The maximum and minimum input voltage limits are shown in [Figure 20](#). The TPSM84209 can be operated between the Maximum and Minimum  $V_{IN}$  limit lines.

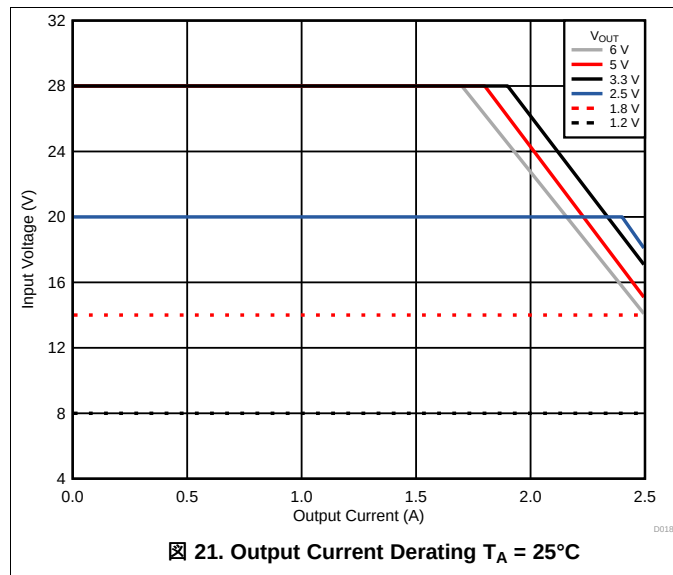
Operating above the Maximum  $V_{IN}$  line may cause the device to skip pulses in order to maintain the regulated output voltage.



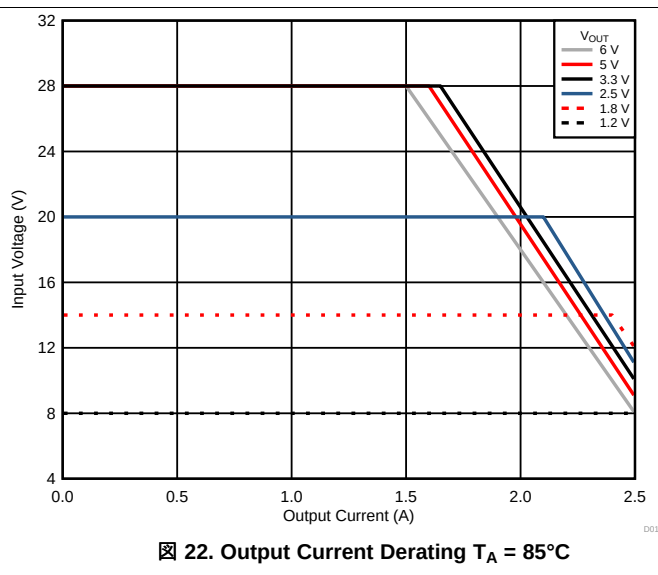
**Figure 20. Input Voltage vs Output Voltage**

### 7.3.7 Output Current Rating

The maximum output current that the TPSM84209 can deliver is a function of input voltage, output voltage, and ambient temperature. The TPSM84209 is capable of delivering up to 2.5 A of output current; however refer to [Figure 21](#) and [Figure 22](#) for maximum current ratings based on operating conditions of the specific application.



**Figure 21. Output Current Derating  $T_A = 25^\circ\text{C}$**



**Figure 22. Output Current Derating  $T_A = 85^\circ\text{C}$**

### 7.3.8 Enable (EN)

The EN pin provides electrical ON and OFF control of the device. When the EN pin voltage exceeds the threshold voltage, the device begins operation. If the EN pin voltage is pulled below the threshold voltage, the regulator stops switching and enters the low-quiescent current state.

The EN pin has an internal pullup-current source, which allows the user to float the EN pin to enable the device. If an application requires control of the EN pin, use open-drain or open-collector output logic to interface with the pin.

Figure 23 shows the typical application of the enable function. Turning Q1 on applies a low voltage to the enable control pin and disables the output of the supply, shown in Figure 24. If Q1 is turned off, the supply executes a soft-start power-up sequence, as shown in Figure 25.

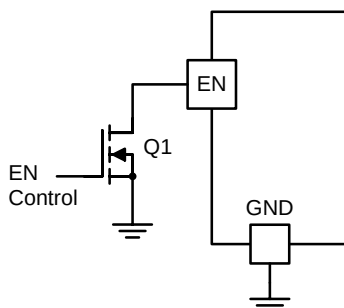
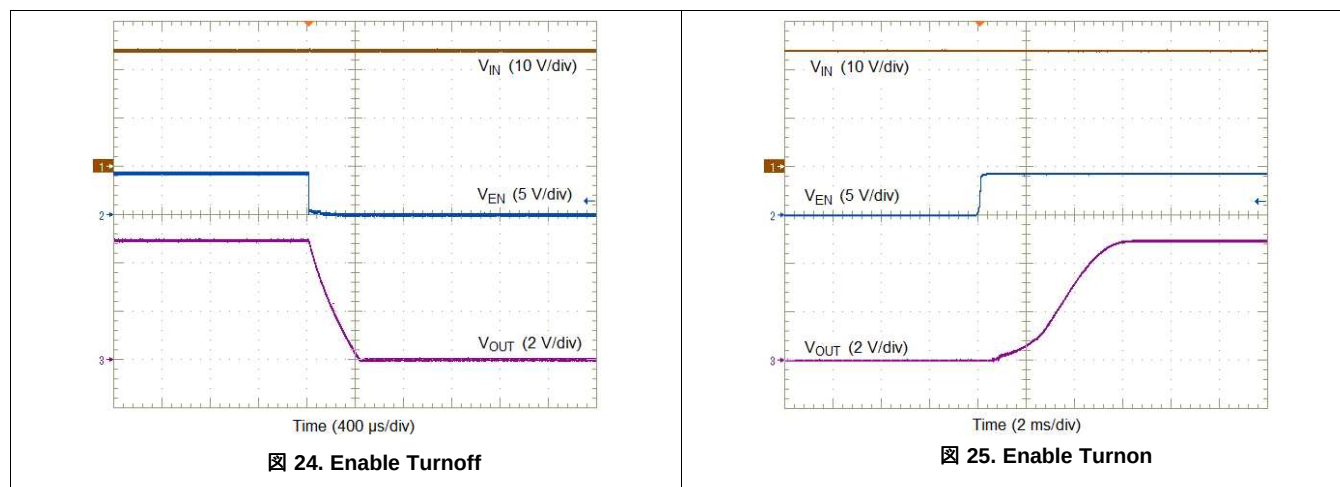


Figure 23. Typical Enable Control



### 7.3.9 Internal Soft Start

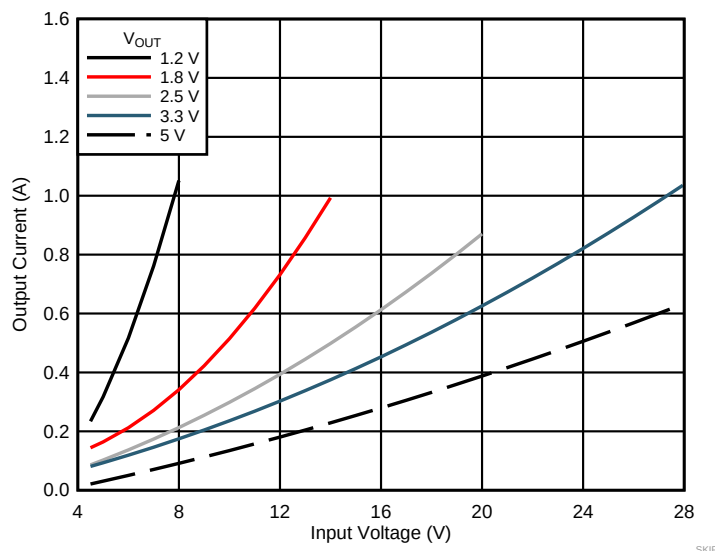
The TPSM84209 device uses the internal soft-start function. The internal soft-start time is set to 5 ms typically.

### 7.3.10 Safe Start-Up Into Prebiased Outputs

The device has been designed to prevent the low-side MOSFET from discharging a prebiased output. During monotonic prebiased start-up, both high-side and low-side MOSFETs are not allowed to be turned on until the internal soft-start voltage is higher than FB pin voltage.

### 7.3.11 Light Load Efficiency / Eco-Mode

The TPSM84209 device is designed to operate in high-efficiency, pulse-skipping mode under light load conditions. As the load current on the output is decreased, a point is reached where the energy delivered by a single switching pulse is more than the load can absorb. This causes the output voltage to rise slightly. This rise in output voltage is sensed by the feedback loop, and the device responds by skipping one or more switching cycles until the output voltage falls back to the setpoint. At very light loads or no load, many switching cycles are skipped. The observed effect during this pulse-skipping mode of operation is an increase in the peak-to-peak ripple voltage and a decrease in the ripple frequency. The load current where pulse skipping begins is a function of the input voltage and output voltage. [Figure 26](#) is a plot of the pulse-skipping threshold current as a function of input voltage for a number of popular output voltages.



**Figure 26. Pulse-Skipping Threshold**

### 7.3.12 Voltage Dropout

Voltage dropout is the difference between the input voltage and output voltage that is required to maintain output voltage regulation while providing the rated output current.

To ensure the TPSM84209 maintains output voltage regulation over the recommended operating range, the minimum recommended input voltage is 4.5 V or ( $V_{OUT} \times 1.3$ ), whichever is greater. However, the TPSM84209 does produce an output voltage when operated below the recommended input voltage range. [Figure 27](#) shows the typical dropout voltage curves for 5-V output at  $T_A = 25^\circ\text{C}$ . (Note: As ambient temperature increases, dropout voltage and frequency foldback occur at higher input voltage.)

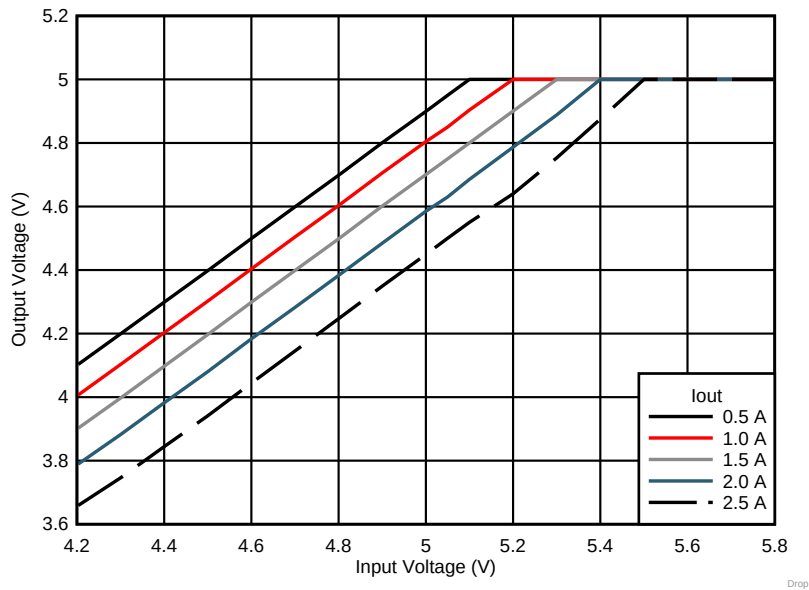


Figure 27. Voltage Dropout

### 7.3.13 Overcurrent Protection

For protection against load faults, the TPSM84209 incorporates output overcurrent protection. Applying a load that exceeds the overcurrent threshold of the regulator causes the output to shut down. Following shutdown, the module periodically attempts to recover by initiating a soft-start power-up as shown in Figure 28. This is described as a hiccup mode of operation, where the module continues in a cycle of successive shutdown and power up until the load fault is removed. During this period, the average current flowing into the fault is significantly reduced which reduces power dissipation. Once the fault is removed, the module automatically recovers and returns to normal operation as shown in Figure 29.

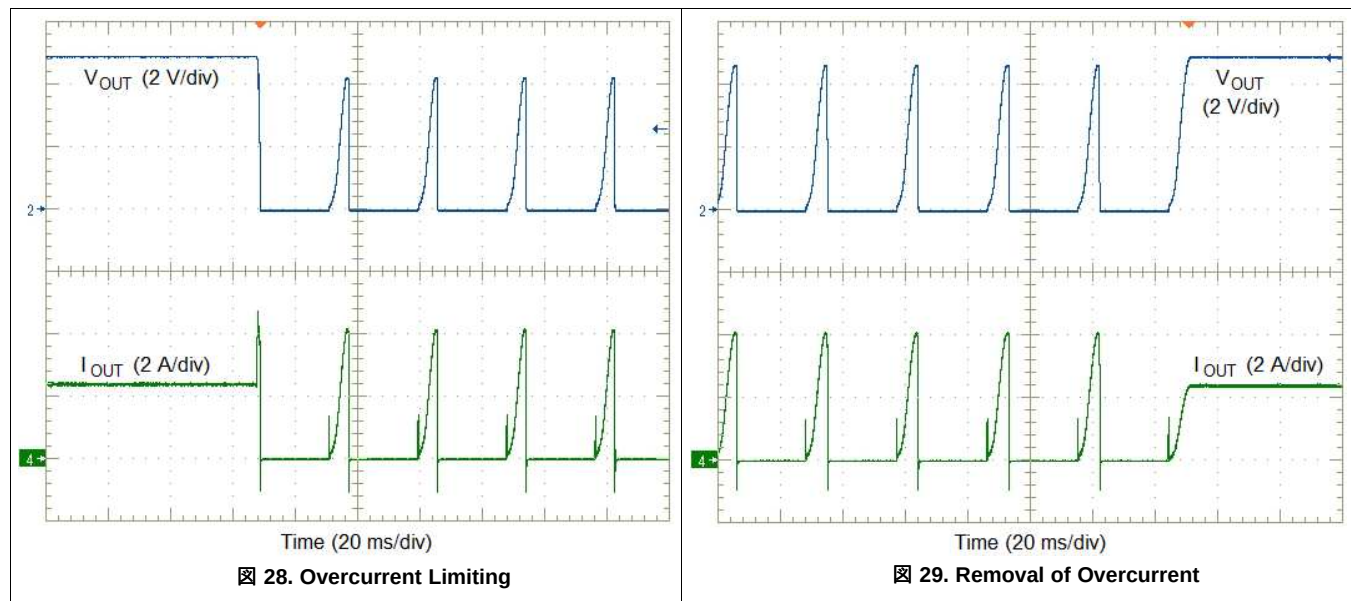


Figure 28. Overcurrent Limiting

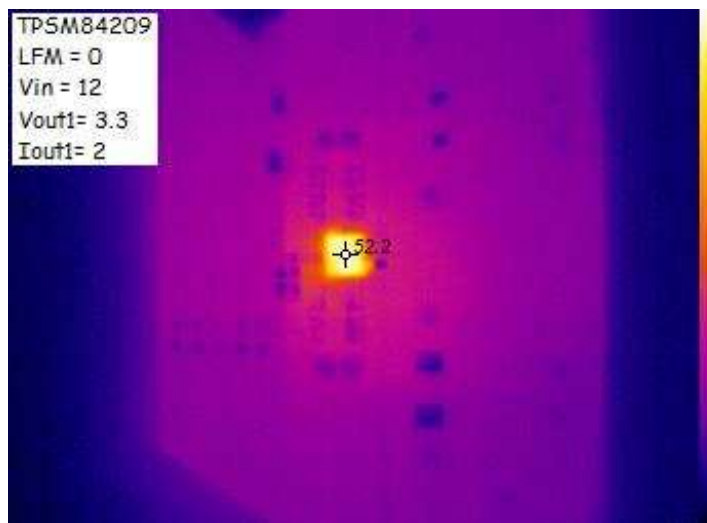
Figure 29. Removal of Overcurrent

### 7.3.14 Output Overvoltage Protection (OVP)

The TPSM84209 incorporates an overvoltage transient protection (OVTP) circuit to minimize output voltage overshoot when recovering from output fault conditions or strong unload transients. The OVTP circuit includes an overvoltage comparator to compare the FB pin voltage and internal thresholds. When the FB pin voltage goes above  $108\% \times V_{ref}$ , the high-side MOSFET is forced off. When the FB pin voltage falls below  $104\% \times V_{ref}$ , the high-side MOSFET is enabled again.

### 7.3.15 Thermal Performance

The typical thermal performance of the TPSM84209 is shown in [Figure 30](#). The thermal image shows the typical temperature rise of TPSM84209 is  $27.2^{\circ}\text{C}$  above ambient when operated at  $V_{IN} = 12\text{ V}$ ,  $V_{OUT} = 3.3\text{ V}$ ,  $I_{OUT} = 2\text{ A}$ , with no airflow (LFM = 0).



$T_A = 25^{\circ}\text{C}$

**Figure 30. Thermal Image**

### 7.3.16 Thermal Shutdown

The internal thermal shutdown circuitry forces the device to stop switching if the junction temperature exceeds  $165^{\circ}\text{C}$  (typ). The device reinitiates the power-up sequence when the junction temperature drops below  $155^{\circ}\text{C}$  (typ).

## **7.4 Device Functional Modes**

### **7.4.1 Active Mode**

When  $V_{IN}$  is above the UVLO threshold and the EN pin voltage is above the EN high threshold, the TPSM84209 operates in the active mode. Normal continuous conduction mode (CCM) occurs when inductor peak current is above 0 A. In CCM, the TPSM84209 operates at a fixed frequency.

### **7.4.2 Eco-Mode Operation**

The TPSM84209 device is designed to operate in high-efficiency, pulse-skipping mode under light load conditions. Pulse skipping initiates when the high-side FET current is less than 500 mA typically. During pulse skipping, the low-side FET turns off when the switch current falls to 0 A. The switching node (SW pin) waveform takes on the characteristics of discontinuous conduction mode (DCM) operation and the apparent switching frequency decreases. As the output current decreases, the perceived time between switching pulses increases.

### **7.4.3 Shutdown Mode**

The EN pin provides electrical ON and OFF control for the TPSM84209. When the EN pin voltage is below the EN threshold, the device is in shutdown mode. In shutdown mode the standby current is 2  $\mu$ A, typically. The TPSM84209 also employs UVLO protection. If  $V_{IN}$  is below the UVLO level, the output of the regulator turns off.

## 8 Application and Implementation

### 注

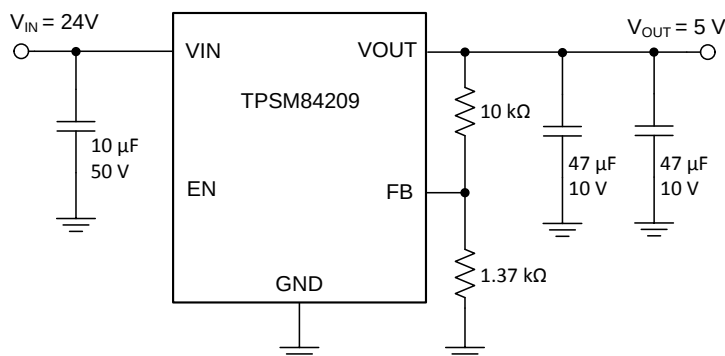
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The TPSM84209 is a synchronous, step-down DC/DC power module. It is used to convert a higher DC voltage to a lower DC voltage with a maximum output current of 2.5 A. The following design procedure can be used to select components for the TPSM84209. Alternately, the WEBENCH® software may be used to generate complete designs. When generating a design, the WEBENCH software utilizes an iterative design procedure and accesses comprehensive databases of components. See [www.ti.com/webench](http://www.ti.com/webench) for more details.

### 8.2 Typical Application

The TPSM84209 requires only a few external components to convert from a wide input-voltage-supply range to a wide range of output voltages. 31 shows a basic TPSM84209 schematic with only the minimum required components.



31. TPSM84209 Typical Application

#### 8.2.1 Design Requirements

For this design example, use the parameters listed in 表 7 and the following design procedures.

表 7. Design Example Parameters

| DESIGN PARAMETER         | VALUE        |
|--------------------------|--------------|
| Input voltage $V_{IN}$   | 24 V typical |
| Output voltage $V_{OUT}$ | 5 V          |
| Output current rating    | 2 A          |

## 8.2.2 Detailed Design Procedure

### 8.2.2.1 Custom Design With WEBENCH® Tools

[Click here](#) to create a custom design using the TPSM84209 device with the WEBENCH® Power Designer.

1. Start by entering the input voltage ( $V_{IN}$ ), output voltage ( $V_{OUT}$ ), and output current ( $I_{OUT}$ ) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at [www.ti.com/WEBENCH](http://www.ti.com/WEBENCH).

### 8.2.2.2 Output Voltage Setpoint

The output voltage of the TPSM84209 device is externally adjustable using a resistor divider ( $R_{FBT}$  and  $R_{FBB}$ ) between  $V_{OUT}$ , FB, and GND. With a fixed value of 10 k $\Omega$  for  $R_{FBT}$ , select the value of  $R_{FBB}$  from [表 1](#) or calculate using [式 2](#):

$$R_{FBB} = \frac{6}{(V_{OUT} - 0.6)} \quad (\text{k}\Omega) \quad (2)$$

For a output voltage of 5 V, the formula yields a value of 1.36 k $\Omega$ . Choose the closest available value of 1.37 k $\Omega$  for  $R_{FBB}$ .

### 8.2.2.3 Input Capacitors

For this design, a 10- $\mu\text{F}$ , X7R dielectric ceramic capacitor rated for 50 V is used for the input decoupling capacitor.

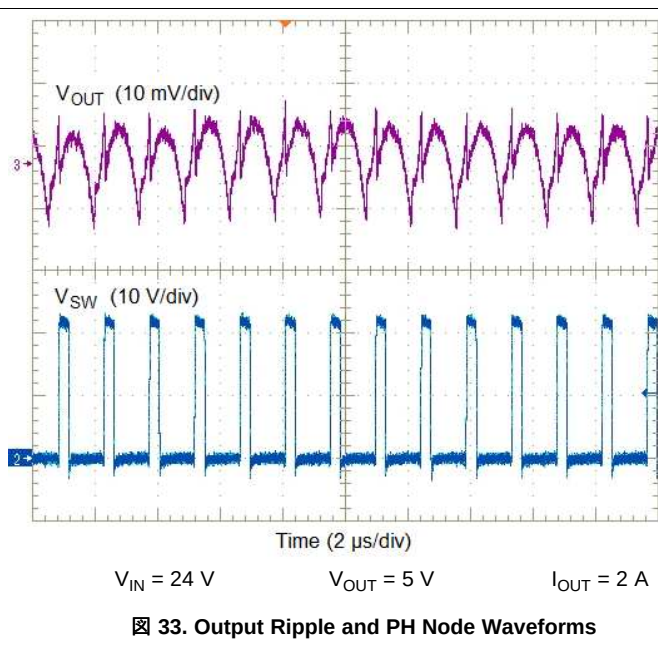
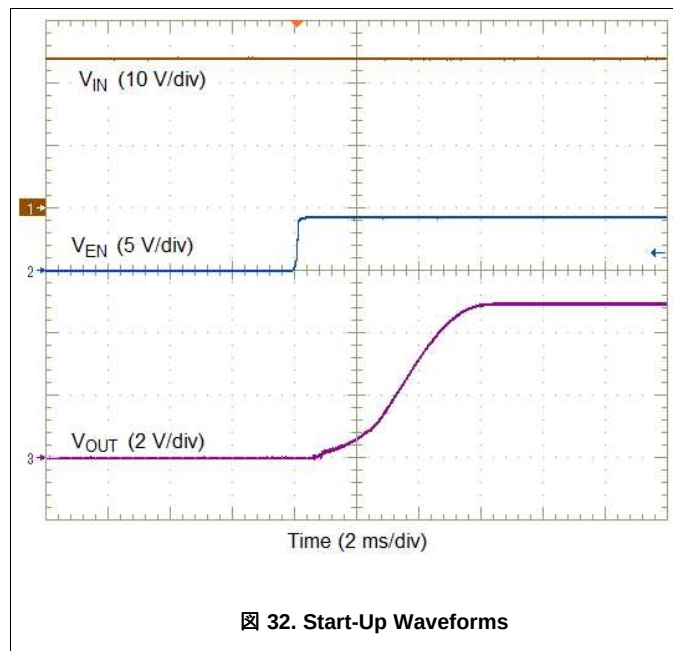
### 8.2.2.4 Output Capacitors

The minimum required output capacitance for a 5-V output is two 47- $\mu\text{F}$  ceramic capacitors. For this design, two 47- $\mu\text{F}$ , X5R dielectric ceramic capacitors rated for 16 V is used for the output capacitance.

### 8.2.2.5 Enable Control

The EN pin provides electrical ON/OFF control of the device. If an application requires control of the EN pin, use open-drain or open-collector output logic to interface with the pin. For this design, a small-signal, low-leakage MOSFET (BSS138) was used.

### 8.2.3 Application Waveforms



## 9 Power Supply Recommendations

The TPSM84209 is designed to operate from an input-voltage-supply range between 4.5 V and 28 V. This input supply must be well regulated and able to withstand maximum input current and maintain a stable voltage. The resistance of the input supply rail must be low enough that an input current transient does not cause a high enough drop at the TPSM84209 supply voltage that can cause a false UVLO fault triggering and system reset.

If the input supply is located more than a few inches from the TPSM84209 additional bulk capacitance may be required in addition to the ceramic bypass capacitors. Typically, a 47- $\mu$ F or 100- $\mu$ F electrolytic capacitor is sufficient.

## 10 Layout

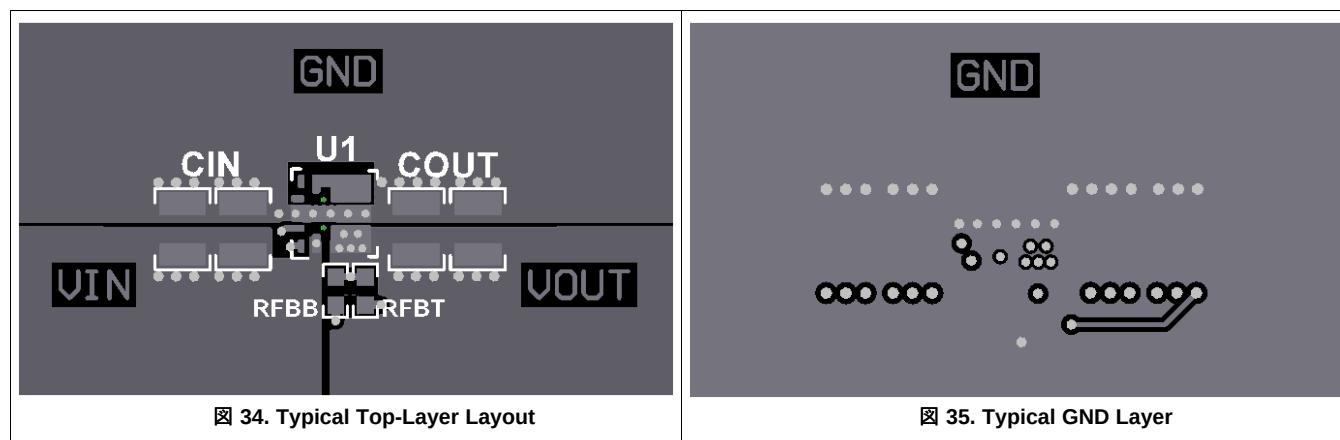
The performance of any switching power supply depends as much upon the layout of the PCB as the component selection. See the following guidelines to design a PCB with the best power conversion performance, thermal performance, and minimized generation of unwanted EMI.

### 10.1 Layout Guidelines

To achieve optimal electrical and thermal performance, an optimized PCB layout is required. [Figure 34](#) and [Figure 35](#), shows a typical PCB layout. Some considerations for an optimized layout are:

- Use large copper areas for power planes (VIN, VOUT, and GND) to minimize conduction loss and thermal stress.
- Place ceramic input and output capacitors close to the device pins to minimize high frequency noise.
- Locate additional output capacitors between the ceramic capacitor and the load.
- Place the output voltage feedback resistors,  $R_{FBT}$  and  $R_{FBB}$ , as close as possible to their respective pins.
- Use multiple vias to connect the power planes to internal layers.

### 10.2 Layout Examples

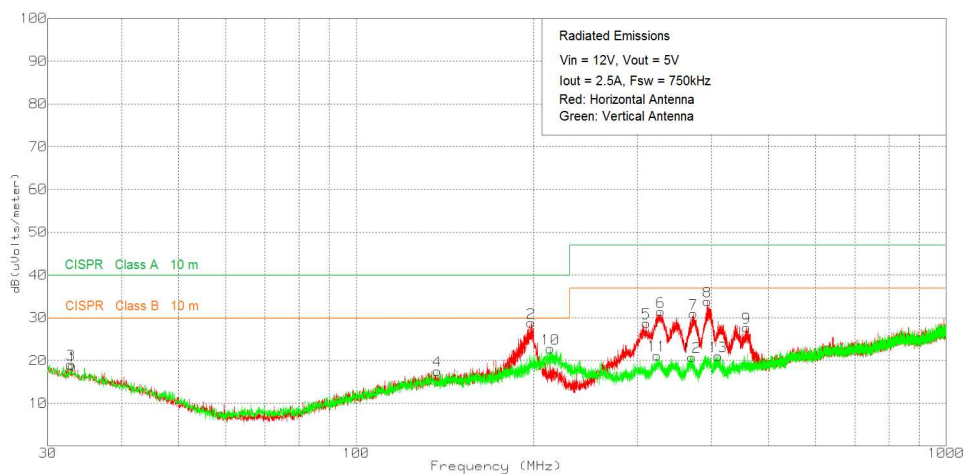


## 10.3 EMI

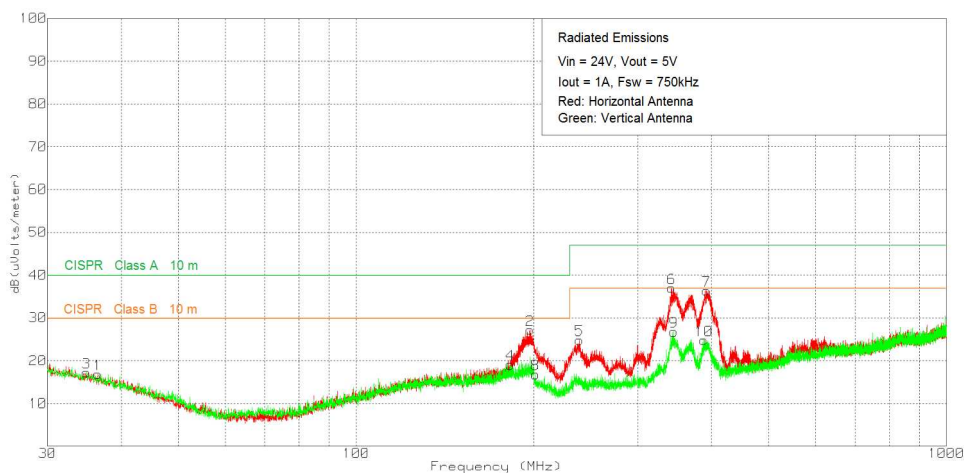
The TPSM84209 is compliant with EN55011 radiated emissions. [Figure 36](#), [Figure 37](#), and [Figure 38](#) show typical examples of radiated emissions plots for the TPSM84209. The graphs include the plots of the antenna in the horizontal and vertical positions.

### 10.3.1 EMI Plots

EMI plots were measured using the standard TPSM84209EVM with no input filter.



**Figure 36. Radiated Emissions 12-V Input, 5-V Output, 2.5-A Load (EN55011 Class B)**



**Figure 37. Radiated Emissions 24-V Input, 5-V Output, 1-A Load (EN55011 Class B)**

## EMI (continued)

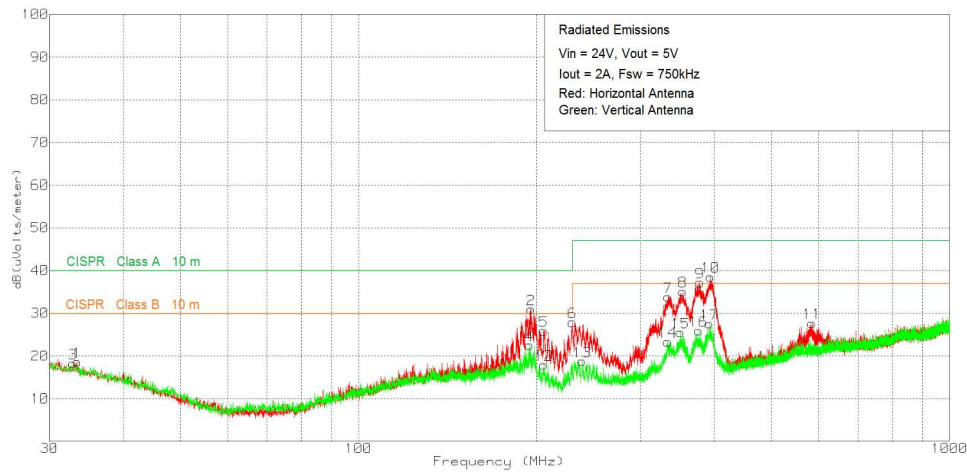


图 38. Radiated Emissions 24-V Input, 5-V Output, 2-A Load (EN55011 Class A)

## 10.4 Package Specifications

表 8. Package Specifications Table

| TPSM84209                   |                                                                           | VALUE | UNIT |
|-----------------------------|---------------------------------------------------------------------------|-------|------|
| Weight                      |                                                                           | 107   | mg   |
| Flammability                | Meets UL 94 V-O                                                           |       |      |
| MTBF Calculated Reliability | Per Bellcore TR-332, 50% stress, $T_A = 40^\circ\text{C}$ , ground benign | 123   | MHrs |

## 11 デバイスおよびドキュメントのサポート

### 11.1 デバイス・サポート

#### 11.1.1 デベロッパー・ネットワークの製品に関する免責事項

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### 11.2 WEBENCH®ツールによるカスタム設計

[ここをクリック](#)すると、WEBENCH® Power Designerにより、TPSM84209デバイスを使用するカスタム設計を作成できます。

1. 最初に、入力電圧( $V_{IN}$ )、出力電圧( $V_{OUT}$ )、出力電流( $I_{OUT}$ )の要件を入力します。
2. オプティマイザのダイヤルを使用して、効率、占有面積、コストなどの主要なパラメータについて設計を最適化します。
3. 生成された設計を、テキサス・インスツルメンツが提供する他の方式と比較します。

WEBENCH Power Designerでは、カスタマイズされた回路図と部品リストを、リアルタイムの価格と部品の在庫情報と併せて参照できます。

通常、次の操作を実行可能です。

- 電氣的なシミュレーションを実行し、重要な波形と回路の性能を確認する。
- 熱シミュレーションを実行し、基板の熱特性を把握する。
- カスタマイズされた回路図やレイアウトを、一般的なCADフォーマットで出力する。
- 設計のレポートをPDFで印刷し、設計を共有する。

WEBENCHツールの詳細は、[www.ti.com/WEBENCH](http://www.ti.com/WEBENCH)でご覧になれます。

### 11.3 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](http://ti.com)のデバイス製品フォルダを開いてください。右上の隅にある「通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

### 11.4 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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## 11.7 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。これらの情報は、指定のデバイスに対して提供されている最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

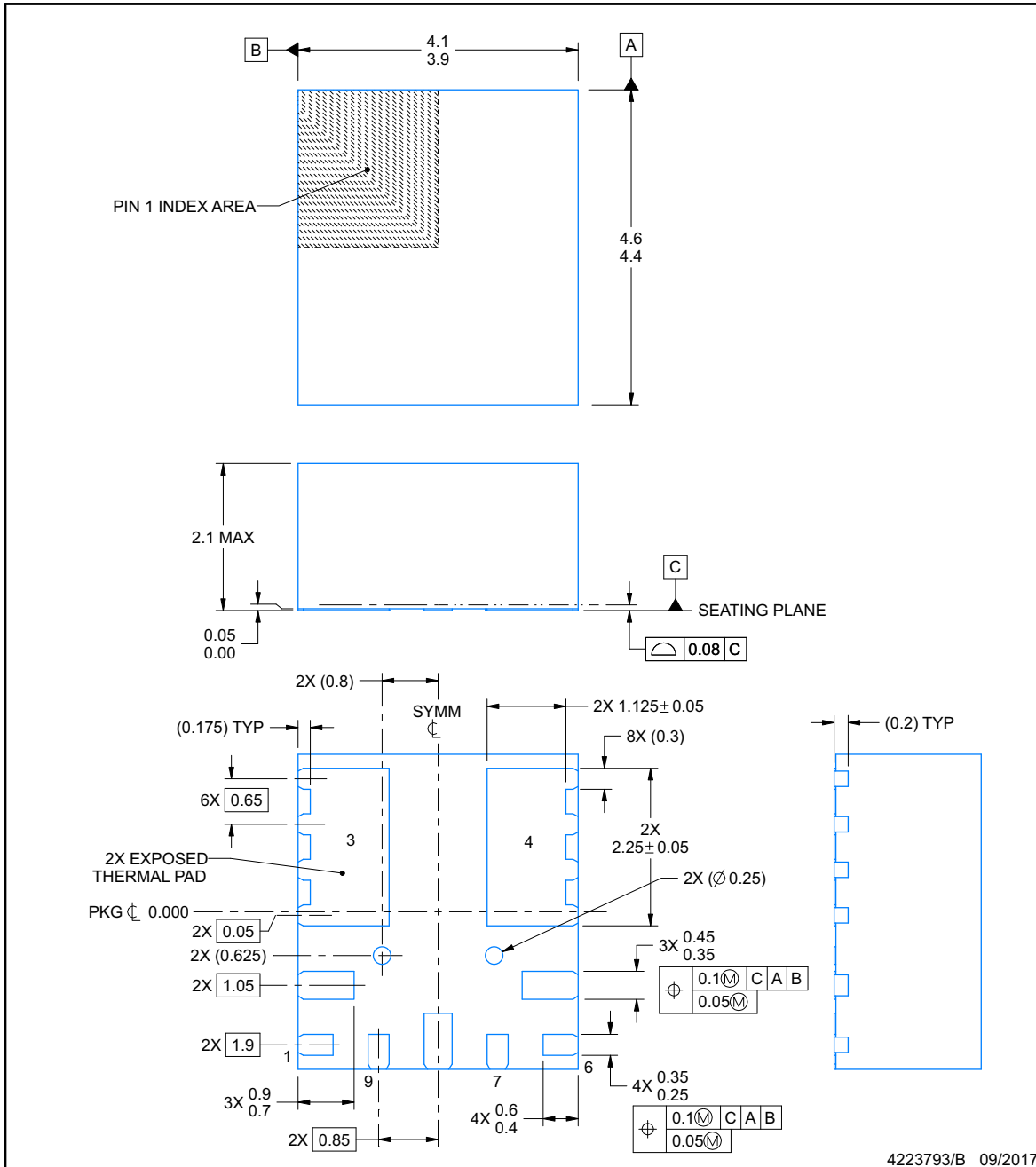


**RKH0009A**

## PACKAGE OUTLINE

**QFN - 2.1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for thermal and mechanical performance.

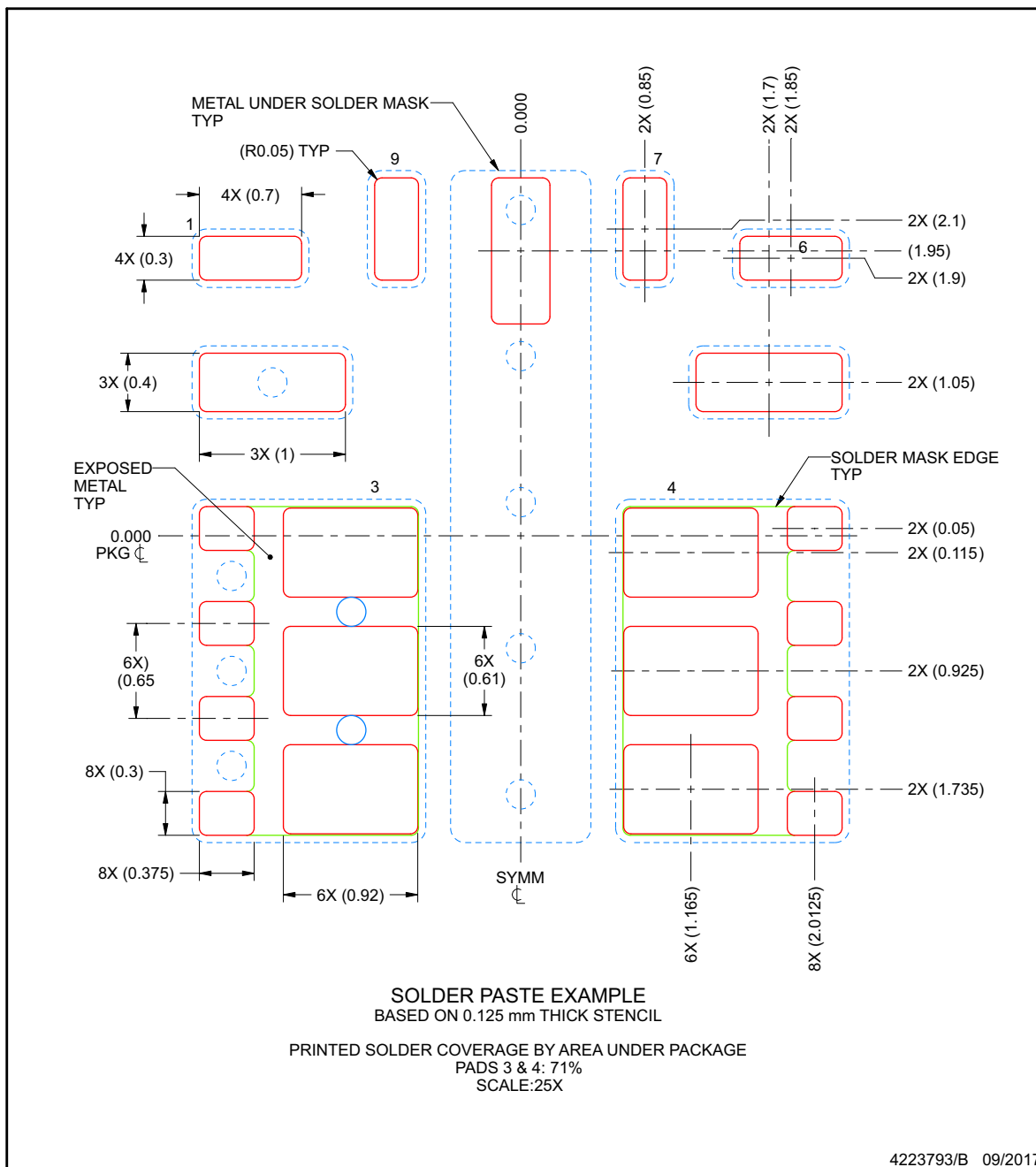


## EXAMPLE STENCIL DESIGN

**RKH0009A**

**QFN - 2.1 mm max height**

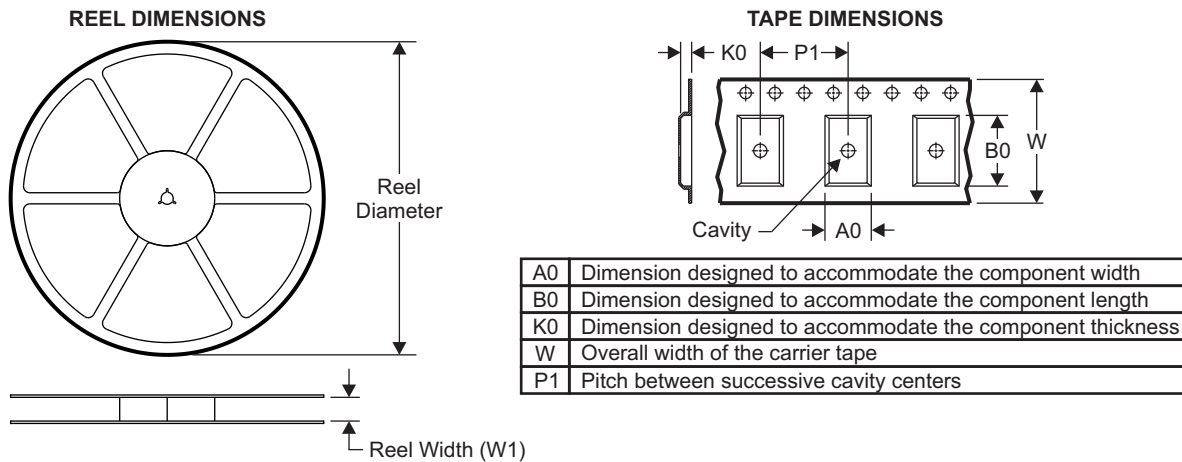
PLASTIC QUAD FLATPACK - NO LEAD



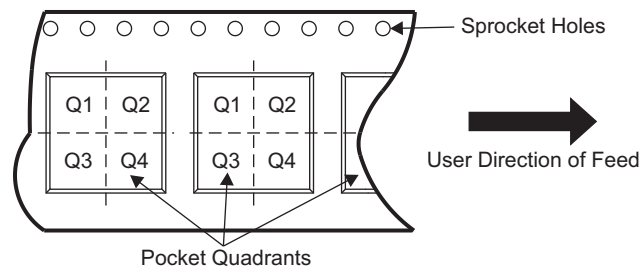
NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## 12.1 Tape and Reel Information

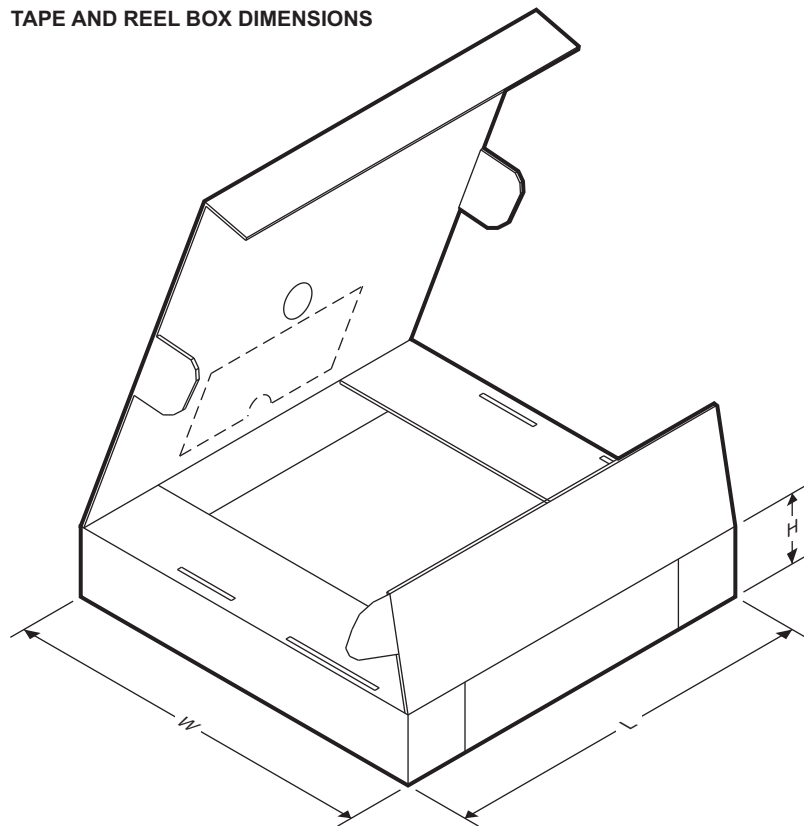


### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| Device        | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPSM84209RKHT | QFN-FCMOD    | RKH             | 9    | 3000 | 330.0              | 12.4               | 4.3     | 4.8     | 2.25    | 8.0     | 12.0   | Q1            |

**TAPE AND REEL BOX DIMENSIONS**



| Device        | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPSM84209RKHT | QFN-FCMOD    | RKH             | 9    | 3000 | 383.0       | 353.0      | 58.0        |

## PACKAGING INFORMATION

| Orderable part number         | Status<br>(1) | Material type<br>(2) | Package   Pins      | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6) |
|-------------------------------|---------------|----------------------|---------------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| <a href="#">TPSM84209RKHR</a> | Active        | Production           | QFN-FCMOD (RKH)   9 | 3000   LARGE T&R      | Yes         | SN                                   | Level-3-260C-168 HR               | -40 to 85    | TPSM84209           |
| <a href="#">TPSM84209RKHT</a> | Active        | Production           | QFN-FCMOD (RKH)   9 | 250   SMALL T&R       | Yes         | SN                                   | Level-3-260C-168 HR               | -40 to 85    | TPSM84209           |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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